IN THE SPECIFICATION:

Please amend paragraph 0013 as follows:

[0013]

In order to solve the problem, the invention according to claim 1 of the present invention provides a SAW device comprising a piezoelectric substrate and an IDT that is formed on the piezoelectric substrate and is made from Al or alloy including Al as a main component, an excited wave being an SH wave, characterized in that the piezoelectric substrate is ~~a quartz flat plate where a cut angle θ of a rotation Y cut quartz substrate is set in a range of $-64.0° < \theta < -49.3°$ in a counterclockwise direction from a crystal Z axis,~~ a rotation Y cut substrate made from a quartz flat substrate, where a cut angle θ of said piezoelectric substrate is a rotation angle of a crystal Z-axis when the piezoelectric substrate is rotated around a crystal X-axis, a direction in which the piezoelectric substrate is rotated from a positive Z-axis side to a positive Y-axis side is a direction in which said cut angle θ is minus, and the cut angle θ is set in a range of $-64.0° < \theta < -49.3°$, and a propagation direction of a SAW is set to ~~90°±5°~~ $(90° \pm 5°)$ to a crystal X-axis, and when a wavelength of the SAW to be excited is represented as λ, an electrode film thickness H/λ standardized by a wavelength of the IDT is set to [[be]] satisfy $0.04 < H/\lambda < 0.12$.

Please amend paragraph 0016 as follows:

[0016]

The invention according to claim 4 provides a SAW device comprising a piezoelectric substrate and an IDT that is formed on the piezoelectric substrate and is made from Al or alloy including Al as a main component, an excited wave being utilized as an SH wave, characterized in that the piezoelectric substrate is ~~a quartz flat plate where a cut angle θ of a rotation Y cut quartz substrate is set to satisfy~~ a rotation Y cut substrate made from a quartz flat substrate, where a cut angle θ of said piezoelectric substrate is a rotation angle of a crystal Z-axis when the

piezoelectric substrate is rotated around a crystal X-axis, a direction in which the piezoelectric substrate is rotated from a positive Z-axis side to a positive Y-axis side is a direction in which said cut angle θ is minus, and the cut angle θ is set in a range of $-61.4^\circ<\theta<-51.1^\circ$ ~~in a counter-clockwise direction from a crystal Z-axis~~, and a propagation direction of a SAW is set to ~~90°±5°~~ (90°±5°) to a crystal X-axis, and when a wavelength of the SAW to be excited is represented as λ, an electrode film thickness H/λ standardized by a wavelength of the IDT is set to satisfy $0.05<H/\lambda<0.10$.